



#131C
7-12-03
Robertson
amdt

Attorney Docket No. 8001-1049
PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Hirokazu MIYAZAKI

Confirmation No. 8771

Serial No. 09/788,596

GROUP 2811

Filed February 21, 2001

Examiner Nitin Parekh

MOUNTING STRUCTURE OF SEMICONDUCTOR
DEVICE AND MOUNTING METHOD THEREOF

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RECEIVED
JUN 30 2003
TECHNOLOGY CENTER 2800

Sir:

Responsive to the Official Action of February 27, 2003,
2001, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 1, replace the last paragraph bridging pages 1 and
2, as follows:

cl
--With reference to Fig. 7, in such a conventional
semiconductor device, a semiconductor chip 21 and a wiring
substrate 25 are connected to each other by welded solder balls
26 of the semiconductor chip 21. Further, resin 29 is injected
into the gap between the semiconductor chip 21 and the wiring
substrate 25 so as to cover the solder balls 26. The resin 29 is
injected for the purpose of alleviating the thermal stress caused
by the difference in the coefficient of thermal expansion between
the semiconductor chip 21 and the wiring substrate 25. The